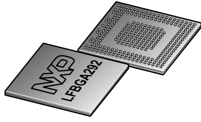

SOT2123-1

LFBGA292, low profile, fine-pitch ball grid array package, 292 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.24 mm body

11 June 2020 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA292
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-11-2014
Manufacturer package code	MV-A300950-00

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	16.9	17	17.1	mm
package width	16.9	17	17.1	mm
seated height	1.17	1.24	1.4	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	292	-	

2 Package outline

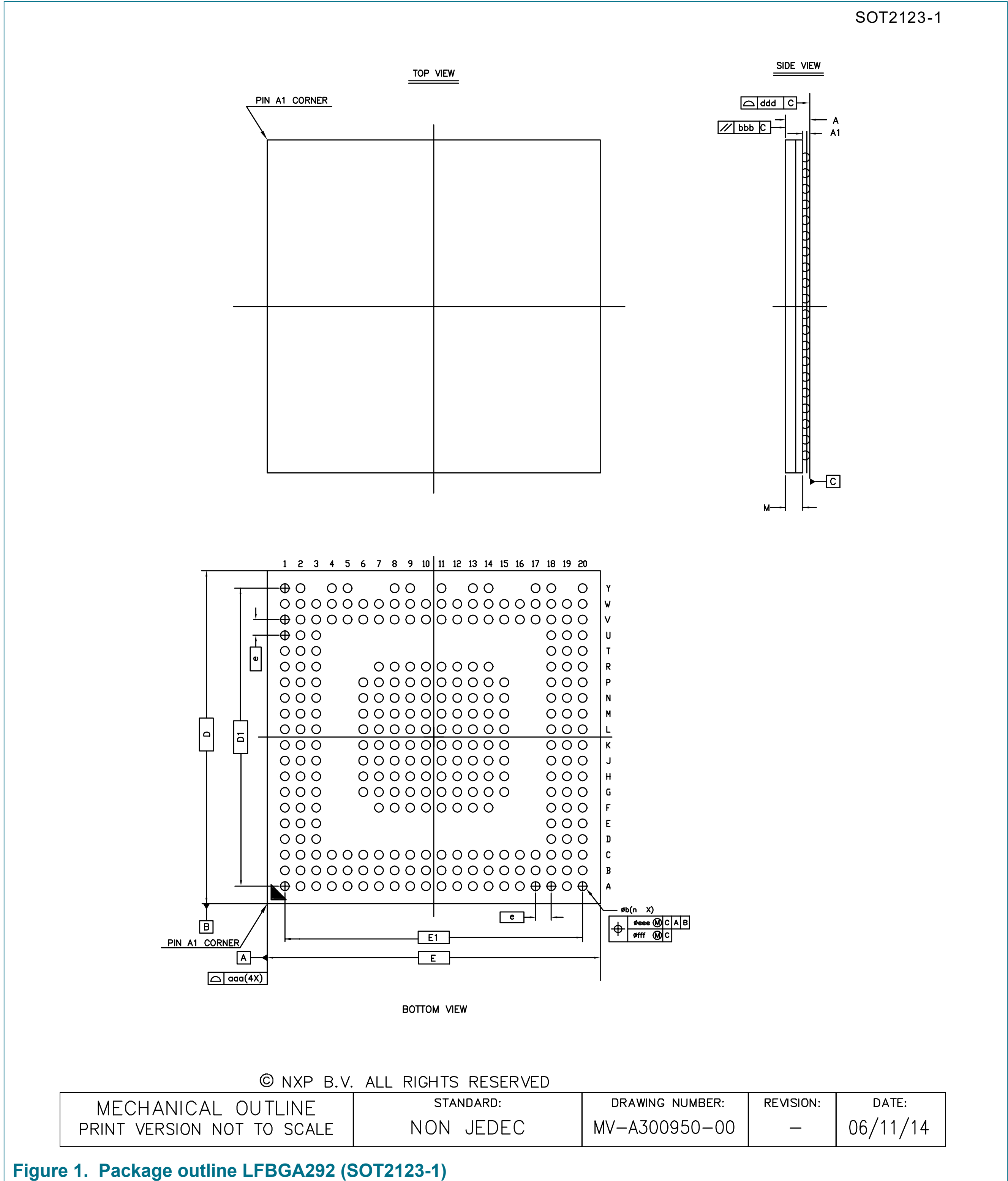

Figure 1. Package outline LFBGA292 (SOT2123-1)

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SOT2123-1

		Symbol	Common Dimensions		
			MIN.	NOM.	MAX.
Body Size:	X	E	16.90	17.00	17.10
	Y	D	16.90	17.00	17.10
Ball Pitch :		e		0.80	
Total Thickness :		A	1.17	1.24	1.40
Body Thickness :		M	0.84	0.89	0.94
Stand Off :		A1	0.30	0.35	0.40
Ball Width :		b	0.40	0.45	0.50
Package Edge Tolerance :		aaa		0.10	
Mold Flatness :		bbb		0.10	
Coplanarity:		ddd		0.14	
Ball Offset (Package) :		eee		0.15	
Ball Offset (Ball) :		fff		0.08	
Ball Count :		n		292	
Edge Ball Center to Center :	X	E1		15.20	
	Y	D1		15.20	

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: MV-A300950-00	REVISION: –	DATE: 06/11/14

Figure 2. Package outline note LFBGA292 (SOT2123-1)

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3 Legal information

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